



Centre for Nanotechnology
and Smart Materials

Development of printed capacitive sensors

From R&D to Process and
Product Engineering

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Summary

- About CeNTI
- Printed electronics: From R&D to Product Engineering
- Technologies: Printed and Embedded Electronics
- R&D and Product Development
- Printed capacitive sensors

High Level Shareholders



Universidade do Minho



Technology Campus



Figures & Facts

- Brainware
 - 45 FTE (Full-time equivalent)
high skilled professionals
 - > 10 Students
 - >15 Patent submissions in the
last 4 years
- Ongoing collaborations
 - > 20 w/ R&D Centers
 - > 50 w/ Companies

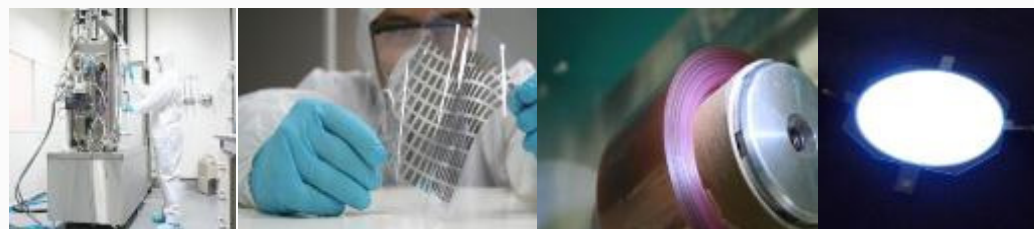


R&D Services

Functional Materials & Solutions



Smart Materials & Systems



Solutions Design & Engineering

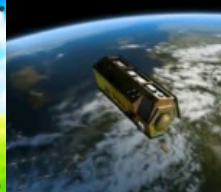


Main Applications

**Health,
Protection &
Well-being**

**Automotive &
Aeronautics**

**Architecture &
Construction**



Several Substrates



Outputs

- Ultra high barrier films
- Gas barrier
- Conductive fibres and films
- Super-hydrophobic and super-oleophobic
- Biocolouring
- High insulation



Outputs

- Selfcleaning
- Abrasion resistant & anti-scratch
- Anti-Slip & Grip-Enhanced Surfaces
- Low weight thermoplastic materials
- High performance adhesives



Outputs

- Drug release materials
- Chemical agents release
- Flame retardant
- **Organic solar cells**
- **Organic LEDs**
- **Electrochromic materials**
- **Heating bands**



Outputs

- Supercapacitors
- Biometric sensors:
 - temperature, heart-rate, motion and touchpads/keypads
- Integrated gas sensors
- Wireless data communication to mobile platforms



PRINTED ELECTRONICS

From R&D to Product Engineering

Scalability: from Demonstrator to Pre-Series

R&D Project

- Proof-of-concept;
- Final Prototype;

Process Development

- Process development;
- Product Design;
- Production Cost Assessment

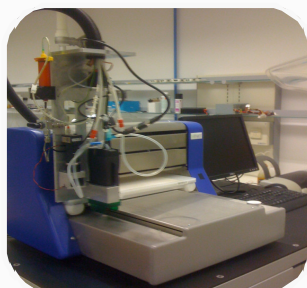
Pre-Series;

- Small Scale Manufacturing;
- Market Test;
- Logistics

Lab scale Printing Technologies



Screen Printing (Sheet
and Rotary)

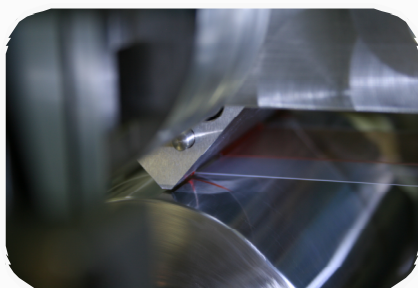


Inkjet Printing



LTE thermal
evaporation

Sheet/Sample



Slot die Coating;
Knife/Doctor blade;
Spray and Dip coating



R2R Gravure



Lamination & Encapsulation

R2R

R2R at pilot and semi industrial scale



3DMM Microflex Print Line 300mm



Multi tech print unit

R2R 12m print line:

- Rotary Screen;
- Slot die coating;
- In-line corona and cleaning;
- 3m N2 thermal treatment;
- Double lamination;

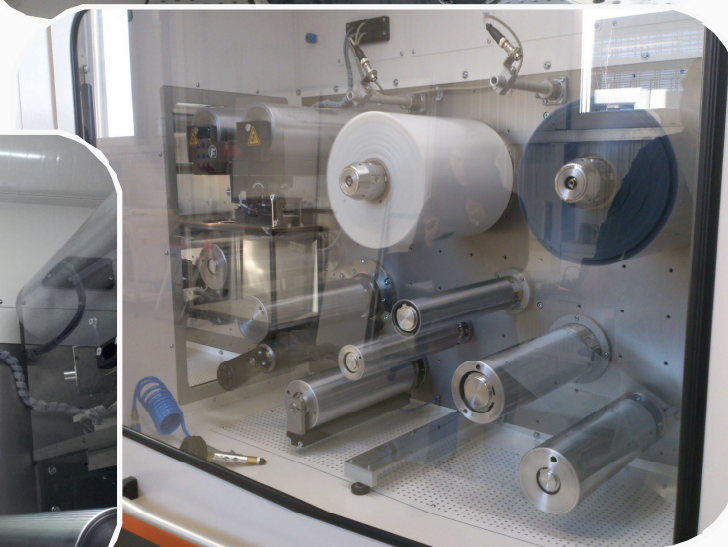
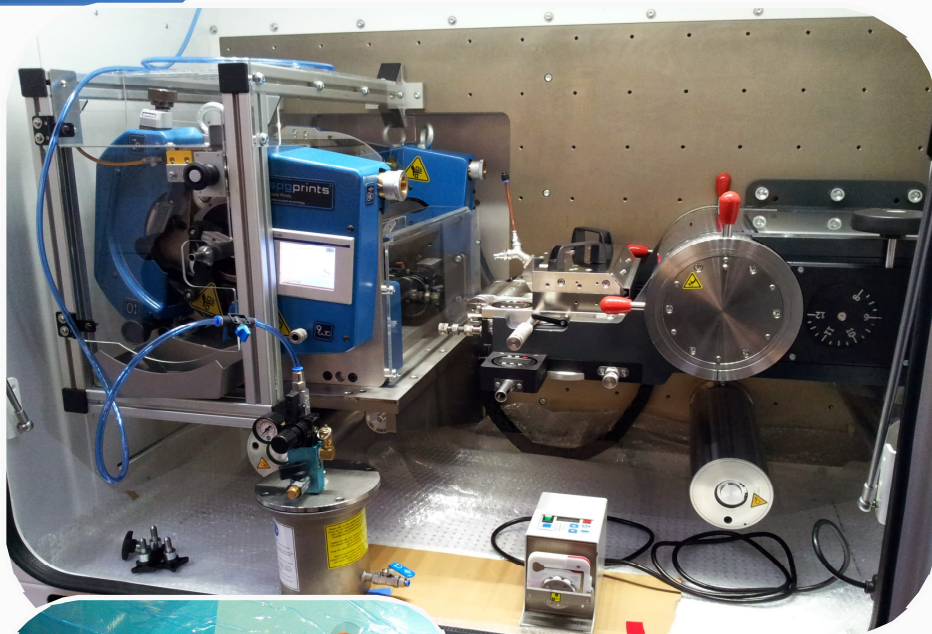
Multi-technology print unit:

- Foulard;
- Gravure printing;
- Knife coating;
- Doctor Blade;
- Slot die coating;
- Micro-roller coating;
- Thermal curing (1m);
- Lamination;



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R2R at pilot and semi industrial scale



Synergy with R2R Vacuum Coating

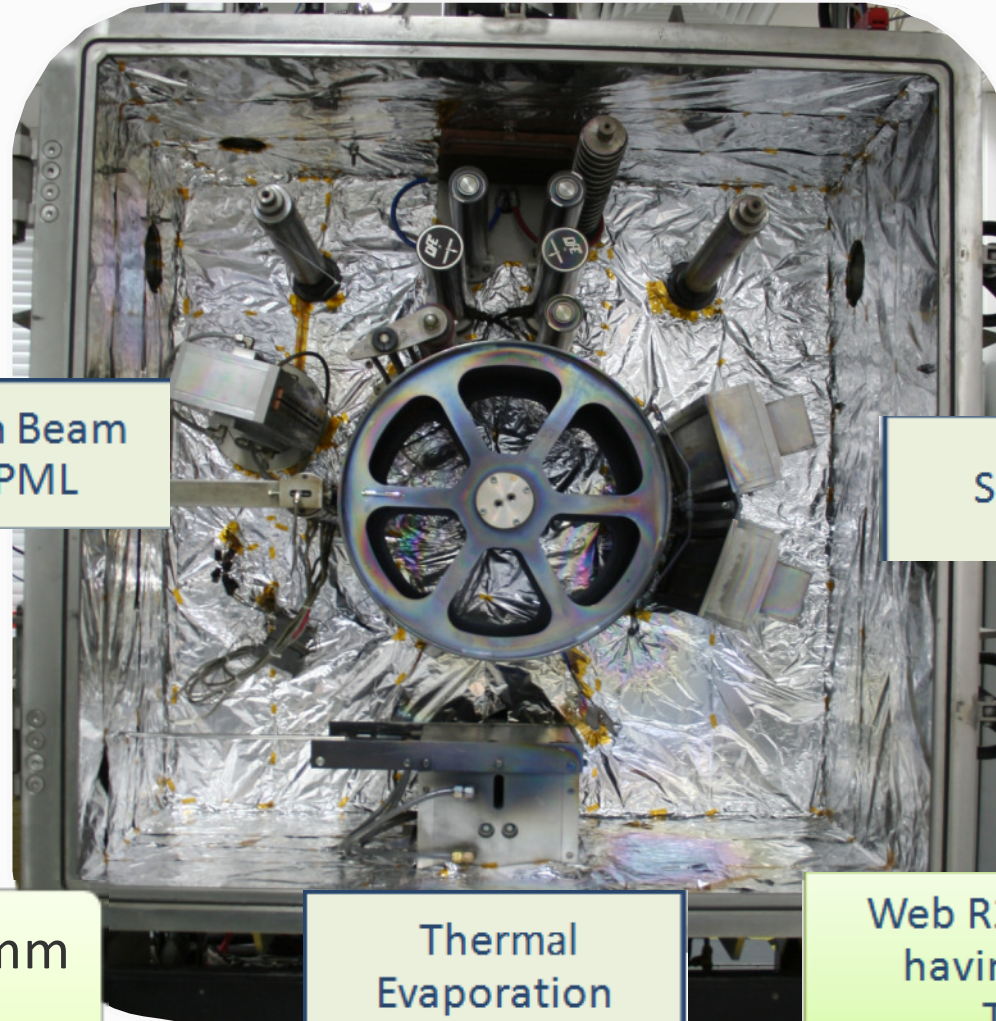
Electron Beam
with PML

Sputtering

100-500mm
R2R

Thermal
Evaporation

Web R2R vacuum system
having 3-line Coating
Technologies



Synergy with R2R Vacuum Coating

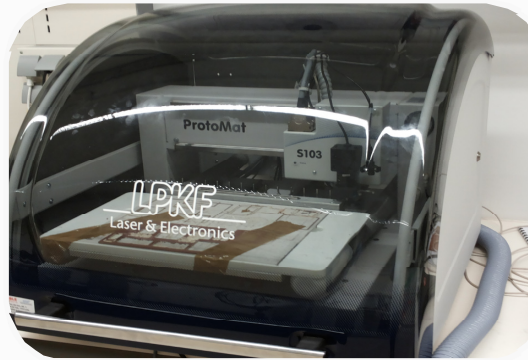
- ▶ **Lab-scale research** needs to consider the **process requirements** given by the 2nd step up-scaling;
- ▶ **Pilot scale** is required to **assess the feasibility of the printing/processing** of a given device and the final product (assembling and integration step);
- ▶ Assessing the **viability of intermediate assembling steps** is key for determining the **feasibility of the process as whole**.



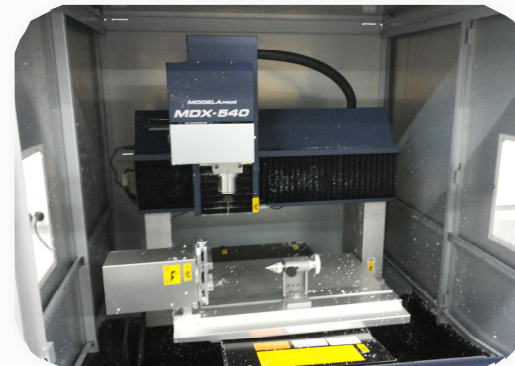
Process development



SMT
Technologies



FABLAB



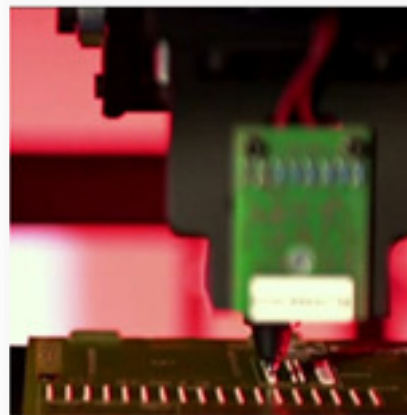
Machining and Finishing

Scalability: sample to product

1st step



2nd step



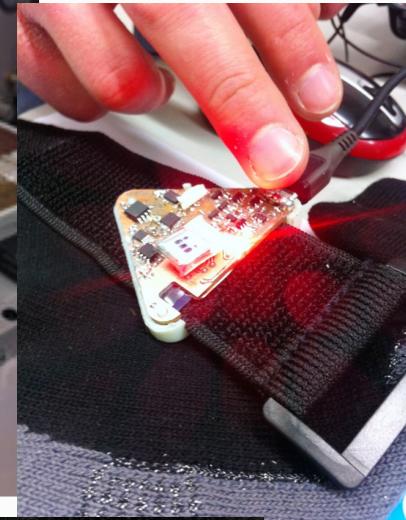
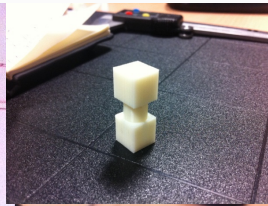
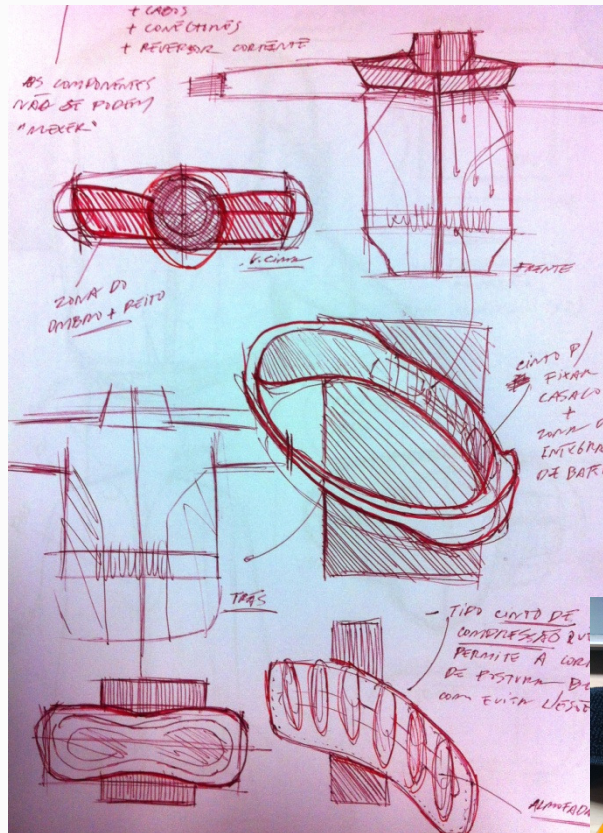
TP LEDs
Smart Pillow



CEN TI

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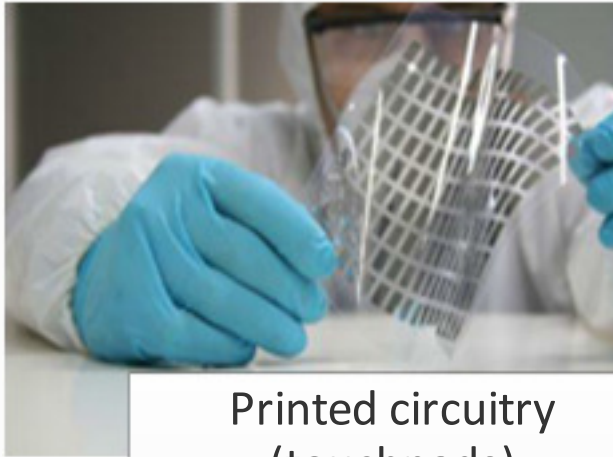
Scalability: sample to product



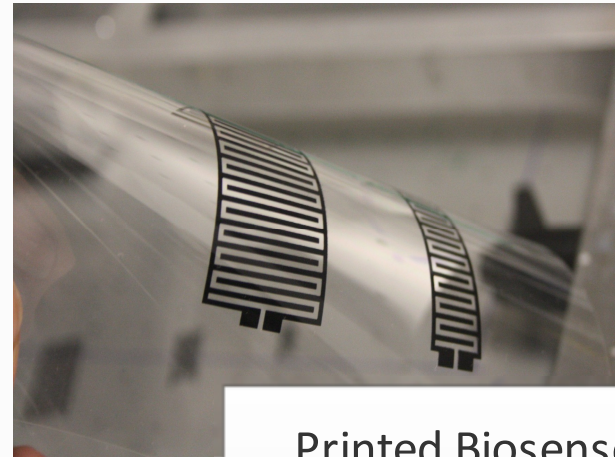
TECHNOLOGIES

Printed and Embedded Electronics

Printed Circuitry/Elements



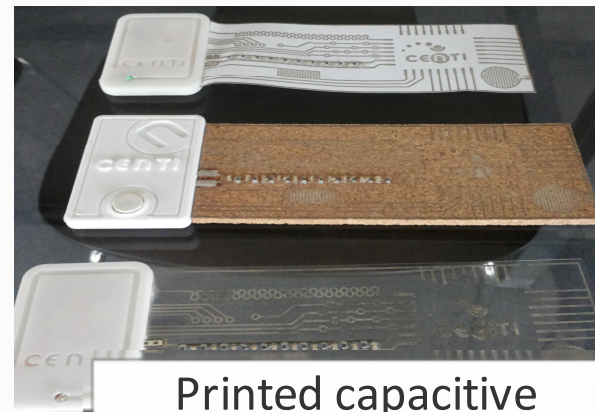
Printed circuitry
(touchpads)



Printed Biosensors



Stretchable



Printed capacitive
sensors

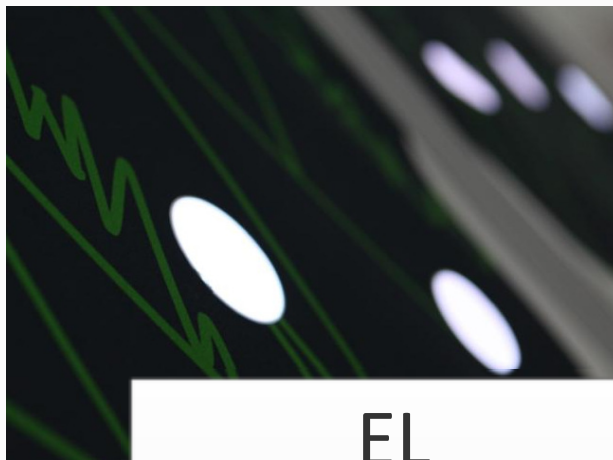
Devices



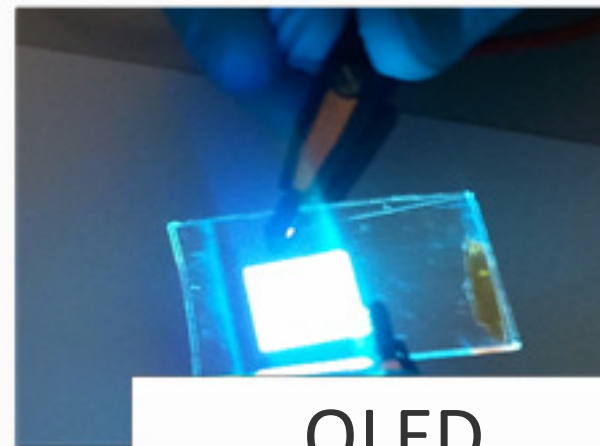
OPVs



Electrochromic

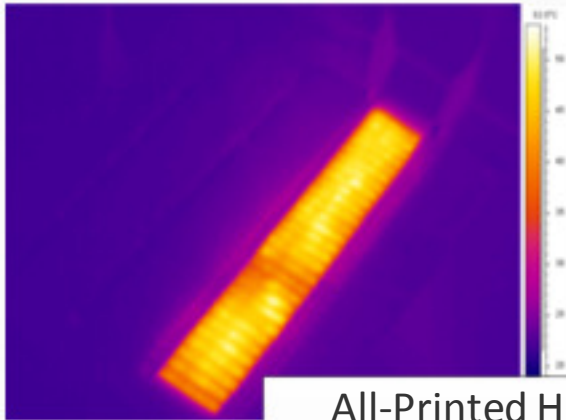


EL

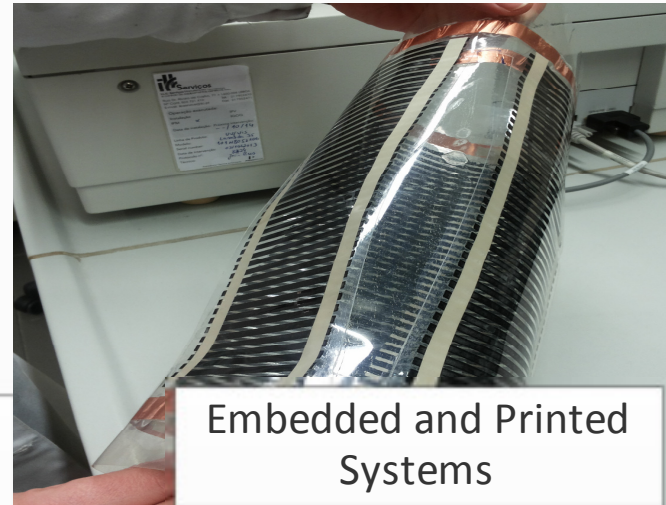


OLED

Devices



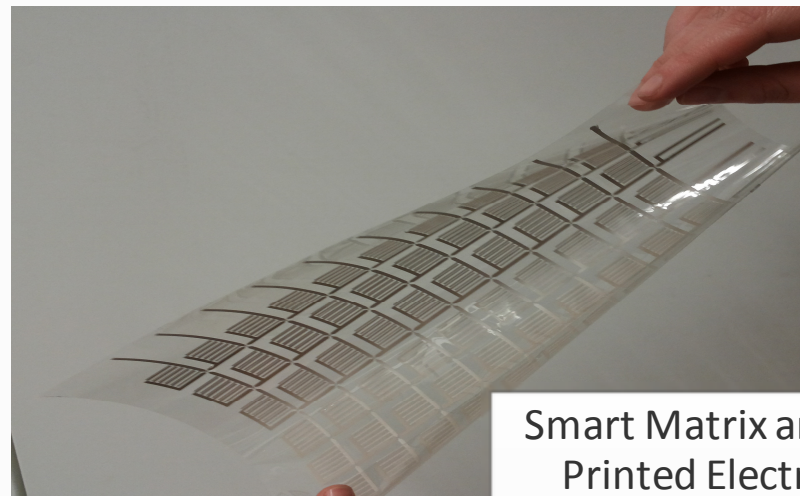
All-Printed Heating Elements



Embedded and Printed Systems



Software and Hardware Development



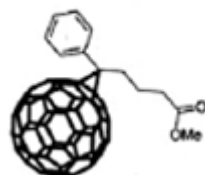
Smart Matrix and Fully Printed Electronics

R&D PROJECTS

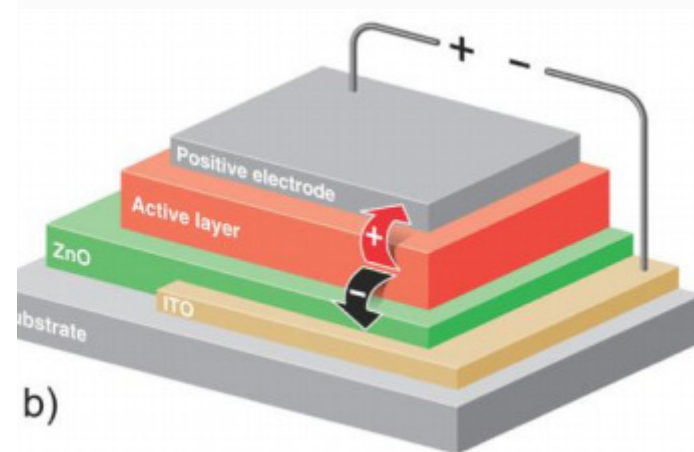
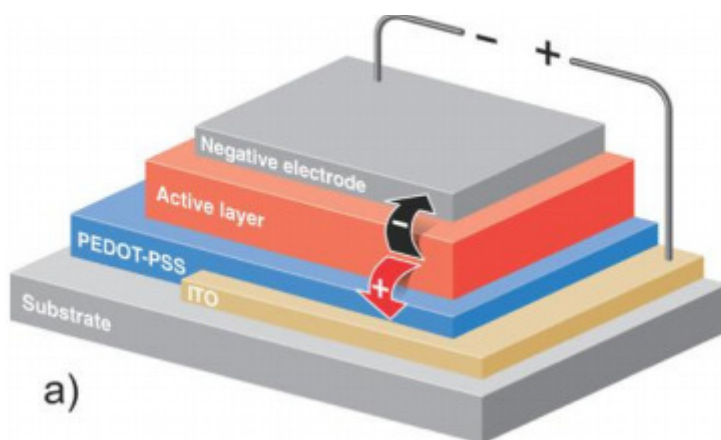
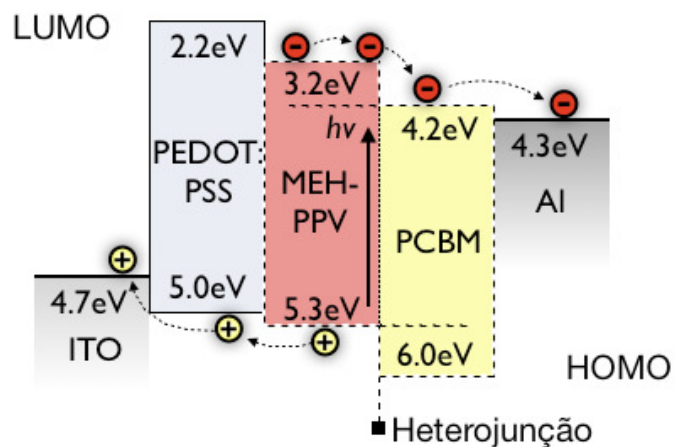
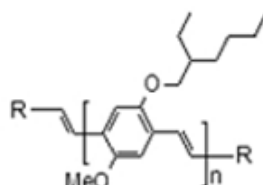
R&D Organic and Printed Photovoltaic
Cooperation with University of Aveiro

Organic Photovoltaic Devices

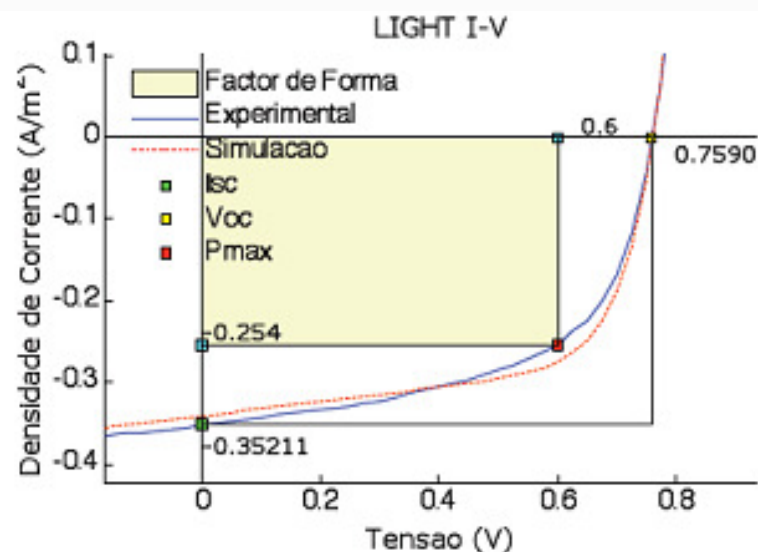
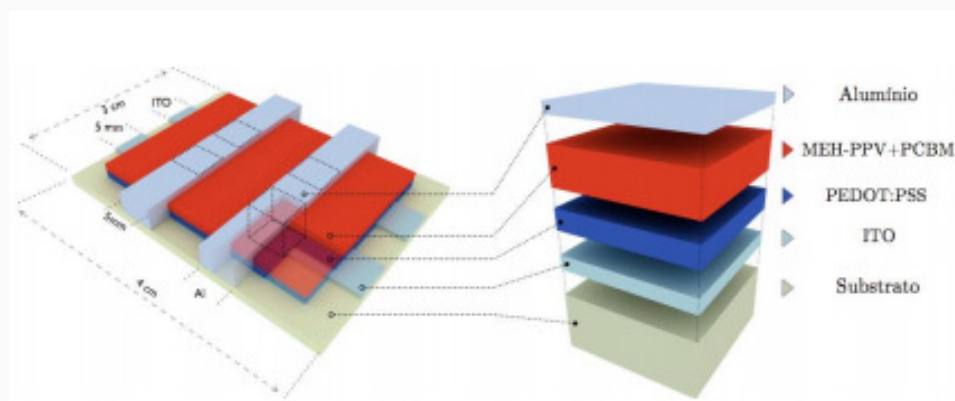
PCBM



MEH-PPV

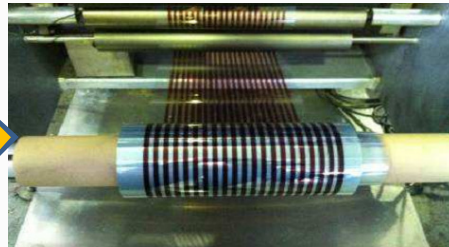
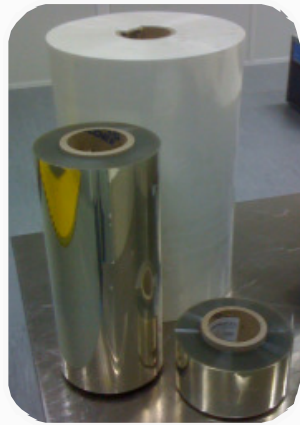


Organic Photovoltaic Devices

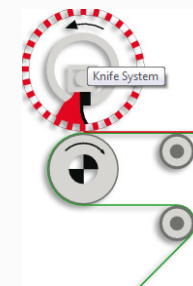
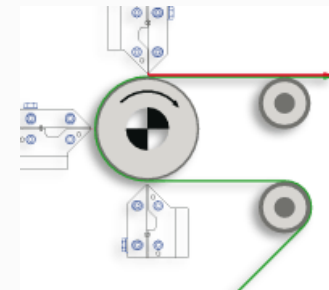


	Extrapolado	Light	Dark
Célula LargeArea	J _{SC} (A/m ²)	0.35	-
	V _{OC} (V)	0.76	-
	J _{Máx} (A/m ²)	0.25	-
	V _{Máx} (V)	0.43	-
	RS (Ω)	136	1.2k
	RP (Ω)	44k	538k
	FF (%)	57.01	
	P _{inc} (W)	1.5x10 ⁻³	
	P _{Máx} (W)	6.1x10 ⁻⁵	
	η (%)	2.76	

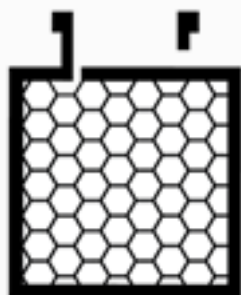
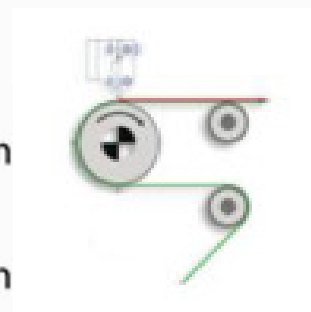
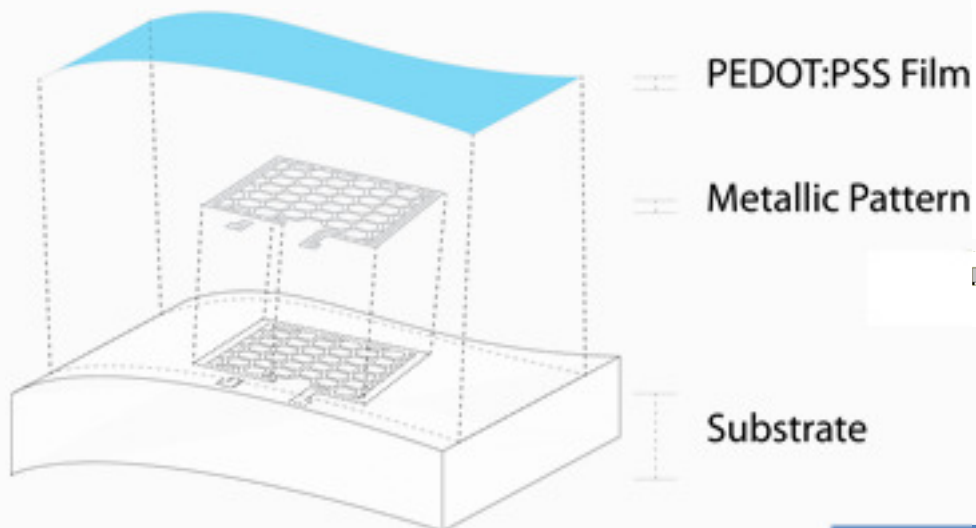
Organic Photovoltaic Devices



- Up scaling R&D processes to R2R processing methodologies;
- The process targets the optimization of R2R process conditions to achieve the same merit figures as attained in R&D trials
- Replacing ITO thin films – “All-printed concept”
- Modularity and mechanical and performance stability



Processing thin hybrid films



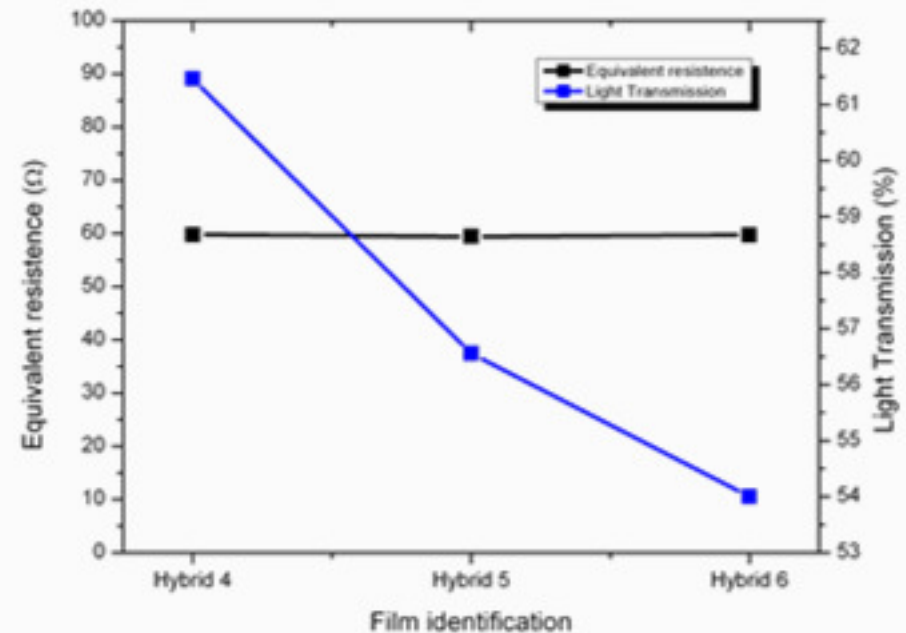
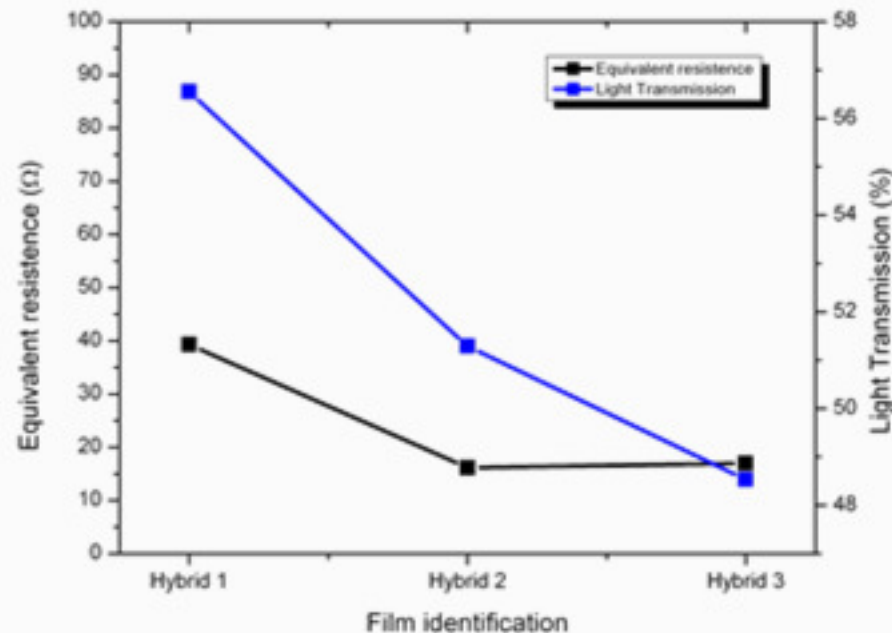
I




II

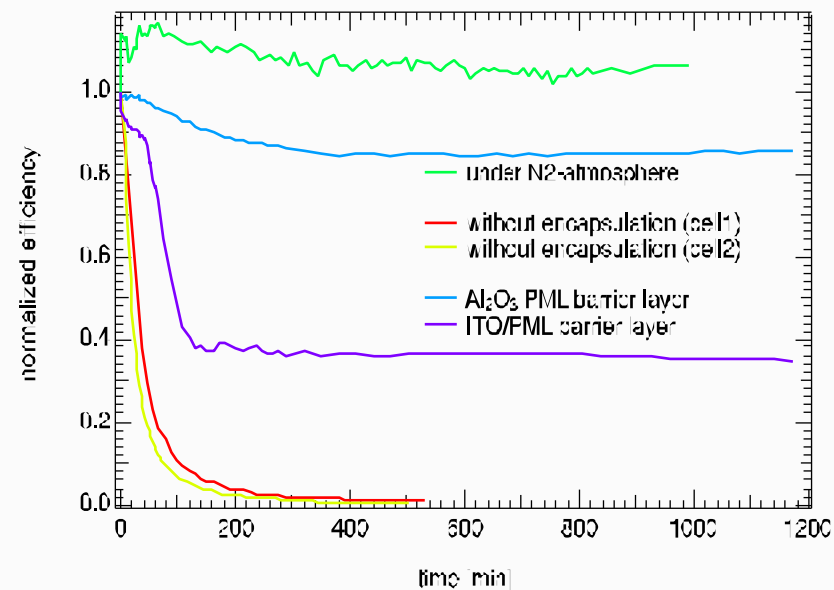
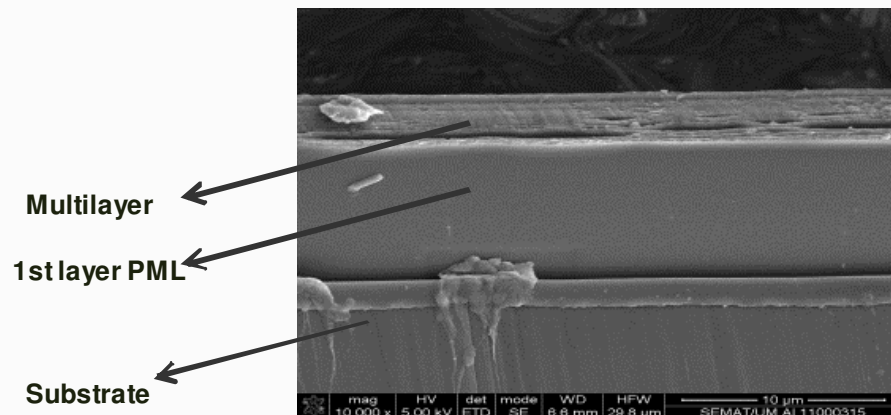
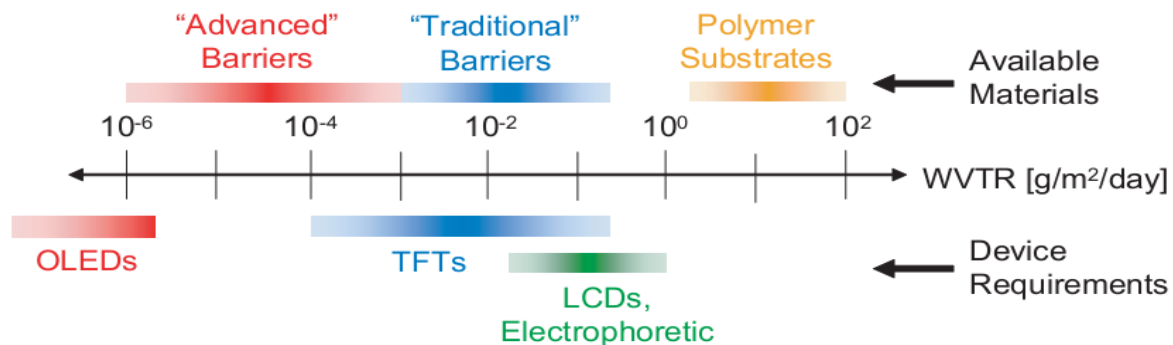
Pattern	Identification (Hybrid)	Line Width (μm)
I	1	350
	2	700
	3	1000
II	4	350
	5	700
	6	1000

Processing thin hybrid films



-  Comparing the value of light transmission and resistance for all hybrid films, it is visible that hybrid film 1 has the best results.

Organic Photovoltaic Devices



PRODUCT DEVELOPMENT

From R&D to Prototyping and Pre-Series

Sensor Tile



- Ceramic tile with an embedded light piezoelectric switch –*light switch* embedded on the tile structure
- Results: International patent held by Dominó.
- CE certified product

TP LEDs and PV Curtain



- Integrated flexible PV modules and LED lighting;
- CeNTI: Control electronics for PV, battery, light-sensor and textile integrated LED (3mm)
- Results: Product to be commercialized



- Development interactive surfaces based in printed electronics integration and substrate functionalization
- Integrate sensors (ex: temperature, pressure, capacitive sensing, piezoelectric);
- Miniaturized sensors;
- Development of electronics for aquisition, treatment and signal transmission

YEXS – Your Extreme Experience



- Multifunctional climbing jacket with integrated electronics (biometric sensors and emergency heating systems)
- CeNTI: Integrated Electronics (Biometric sensors and heating systems) and high thermal insulation materials
- Results: Product to be commercialized

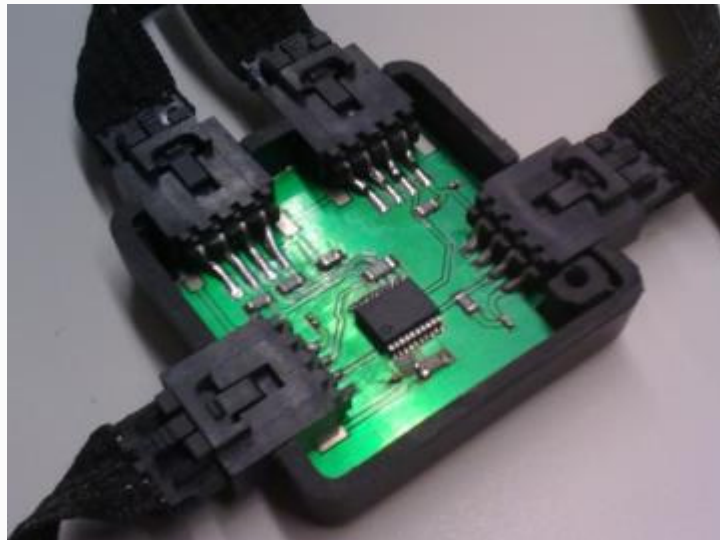
YEXS – Your Extreme Experiences

- Temperature sensors (internal and external)

Sensors



Control unit

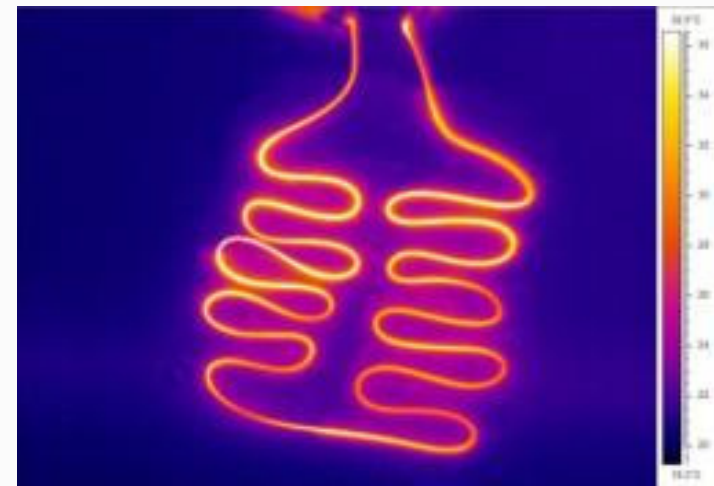


Interconnections



YEXS – Your Extreme Experiences

- Automomous and automated heating systems;
- Textile (weaved, knitted or embroidery) or printable heating systems;
- Integrated temperature management system;



YEXS – Your Extreme Experiences

- ➡ Heart rate measurement

Control unit



Sensor PPG



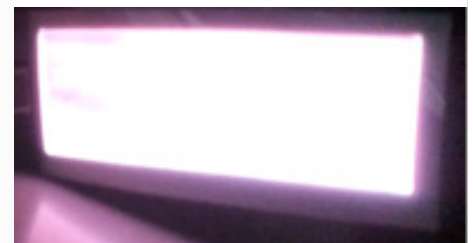
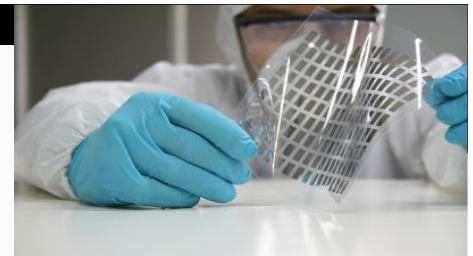
Wall-IT



- Development of multilayer structures for interior walls
- Textile product for rehabilitation of interiors with no major interventions
- Product being industrialized by Termolan

Ongoing Projects

- Flexible PV applications and integration
- Conductive fibres and films
- Super-hydrophobic and super-oleophobic
- Low weight thermoplastic materials
- Organic solar cells and flexible EL
- Organic LEDs
- Electrochromic Devices
- Fully Printed Heating systems and devices
- Fully printed sensor-actuators and printed circuitry



Opportunities

Direct Integration automotive components

Replacement of traditional switches

Fully integrated/printed sensing;

Fully integrated elements (ex. Heating);

Decorative and ambient Lighting

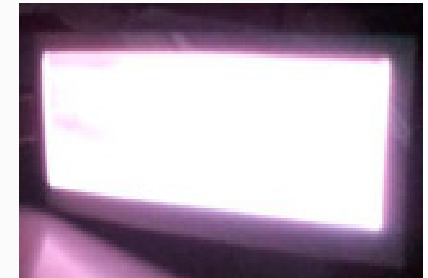
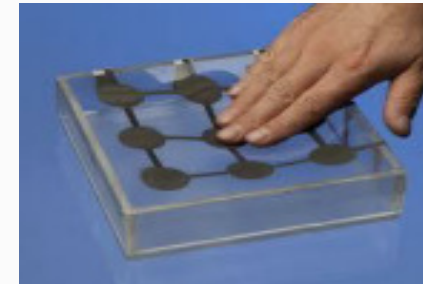
Interior lightning with higher areas, and lower power

Static electricity dissipation

Fibre-level devices

Printed electronics

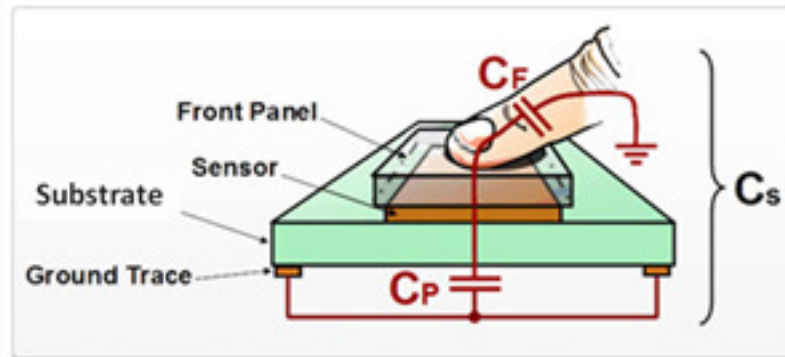
Electronic devices printed in different materials



Printed capacitive sensors

A multidisciplinary approach

Capacitive printed sensors



Main advantages:

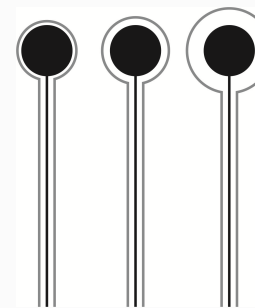
- ▶ New design solutions and easy integration on conventional products;
- ▶ Flexible, lightweight and very thin;
- ▶ No moving parts and no direct contact with the sensor → long lifetime;
- ▶ Simplified manufacturing R2R techniques;
- ▶ Economical and resource-saving process.

Interdigital sensors



liquid level
detection;
dielectric constant
determination

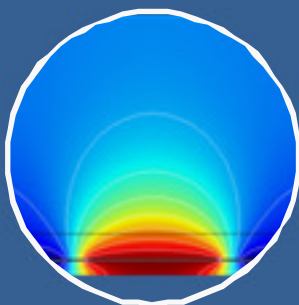
Circle+ring sensors



touch/proximity
sensors

Capacitive printed sensors

An integrated and multi-disciplinary approach



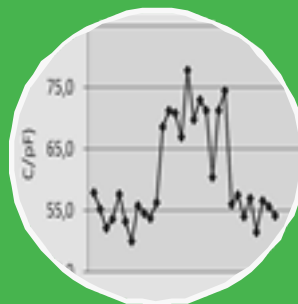
Numerical simulation

Design optimization



Processing

Printing
Lamination
Laser Cutting
etc.



Characterization

Electrical measurement
AFM, profilometry
Optical microscopy



Engineering

Development of systems for acquisition, treatment and transmission of data

Capacitive printed sensors

Numerical simulation

Processing

Characterization

Engineering

Defining physics of phenomena

Maxwell equation:

$$\nabla \mathbf{D} = \rho$$

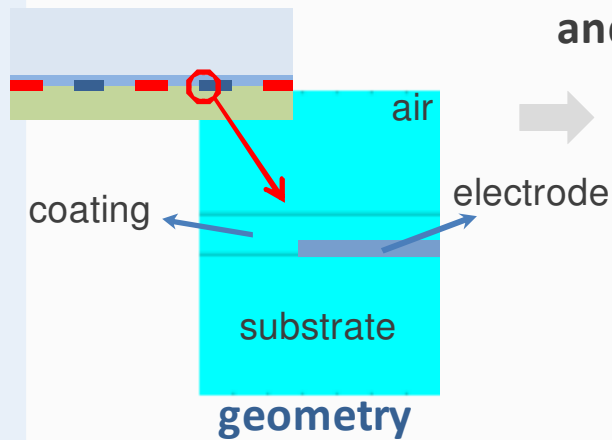
Constitutive relation:

$$\mathbf{D} = \epsilon_0 \mathbf{E} + \mathbf{P}$$

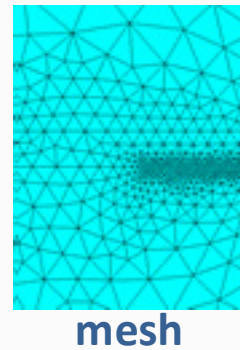
Static conditions:

$$\mathbf{E} = -\nabla V$$

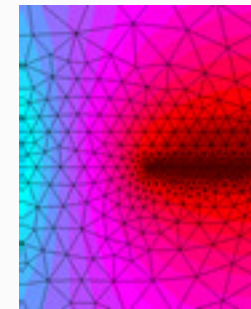
Defining geometry



Defining discretization and solving method



Sensor performance evaluation



Capacitance

FEM provides rapid performance evaluation of electrode systems design

Capacitive printed sensors

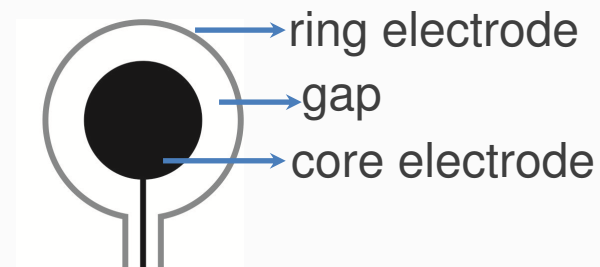
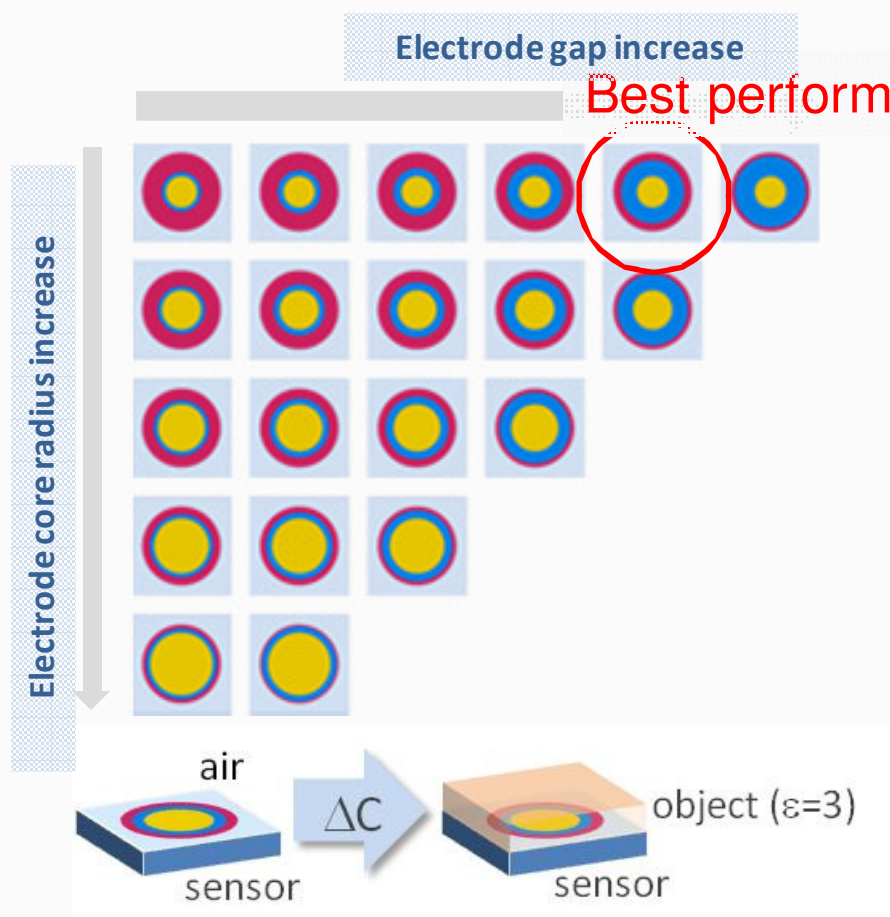
Numerical simulation

Processing

Characterization

Engineering

Touch sensor



		ΔC (%)					
		Gap thickness (mm)					
		1	1.5	2	3	4	5
Core electrode radius (mm)	4	27.8	28.4	28.7	29	29.1	28.9
	5	27.7	28.3	28.6	28.8	28.7	
	6	27.5	28.1				
	7	27.3	27.7	27.7			
	8	26.5	26.0				

Best performance

Capacitive printed sensors

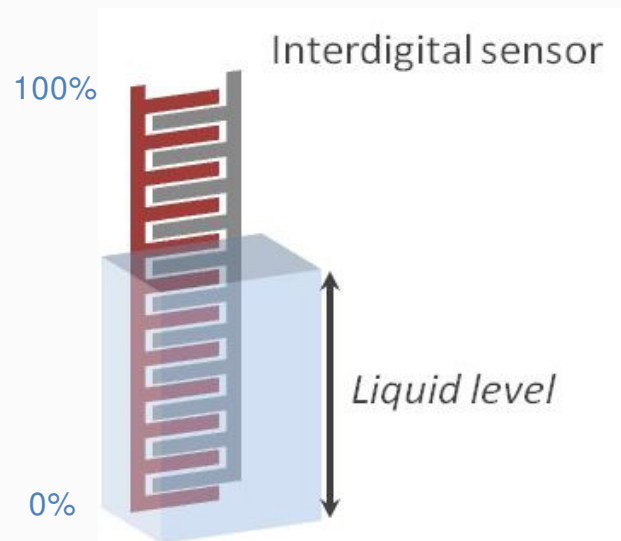
Numerical simulation

Processing

Characterization

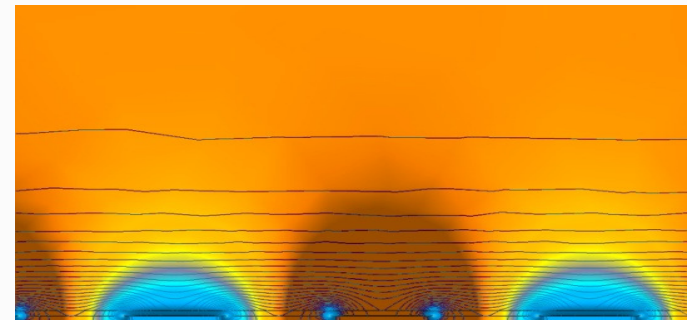
Engineering

Liquid level sensor

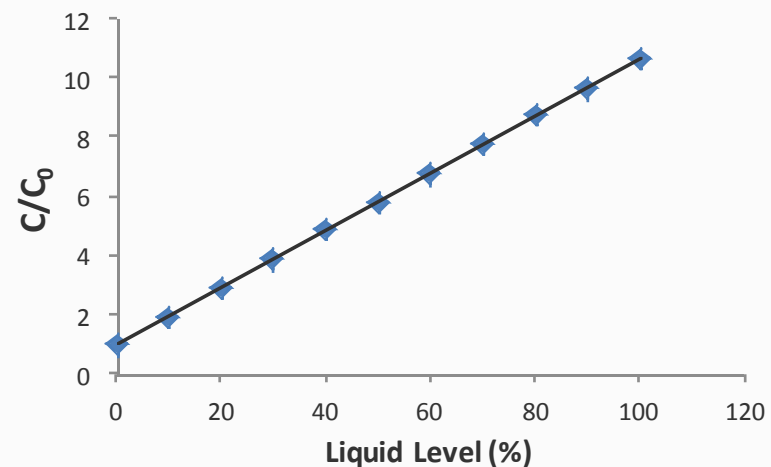


Substrate: PET (75 μ m)
Encapsulator: PET (75 μ m)
Liquid: Water ($\epsilon=80$)

Electric potential



Capacity vs Liquid Level



Capacitive printed sensors

Numerical simulation

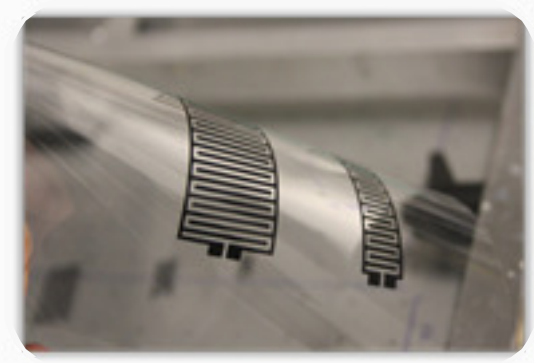
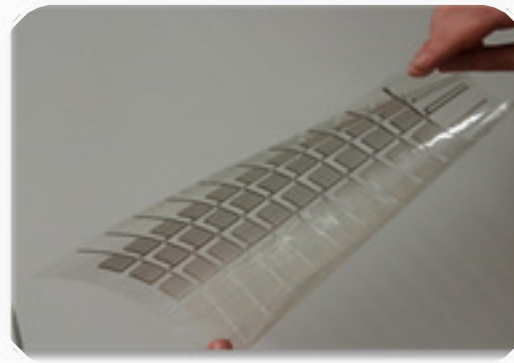
Processing

Characterization

Engineering

Different kinds of substrates:

- ▶ Flexible polymeric substrates;
- ▶ Directly on company raw materials/final products (e.g. carbon composite, paper, cork, textiles, etc.).



Capacitive printed sensors

Numerical simulation

Processing

Characterization

Engineering

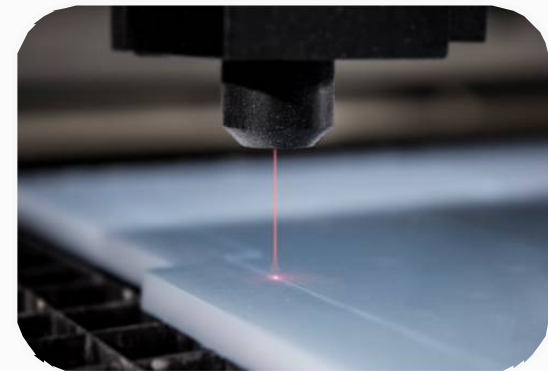
Sheet/sample



Inkjet



Screen-printing



Laser cutting

Capacitive printed sensors

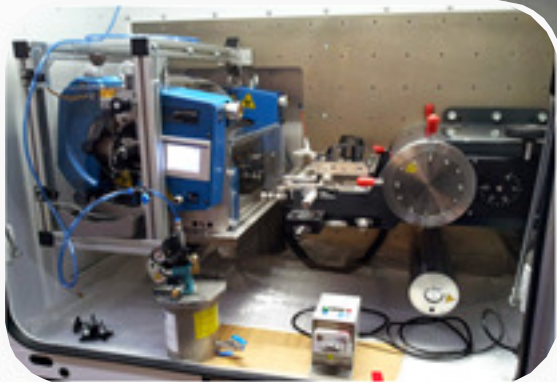
Numerical simulation

Processing

Characterization

Engineering

R2R unity



Rotaryscreen



Slot die



Lamination

Capacitive printed sensors

Numerical simulation

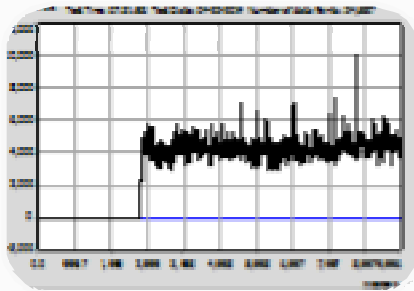
Processing

Characterization

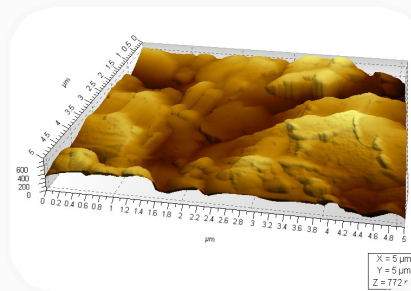
Engineering

Printing quality evaluation

Macrostructure analysis

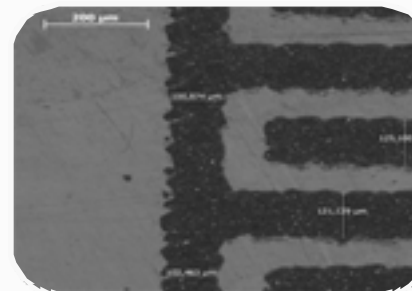


Profilometry



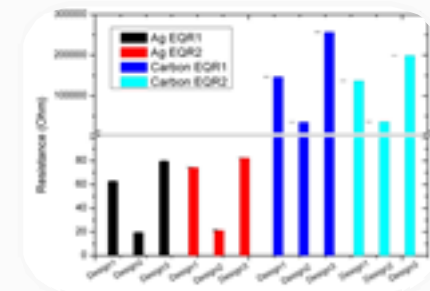
AFM

Lateral resolution



Optical Microscopy

Sheet resistance



4 probe
measurement

- Optimization of process parameters (screen properties, processes rates, curing conditions, etc.)
- Main goals: process reproducibility; low sheet resistance and smooth surfaces.

Capacitive printed sensors

Numerical simulation

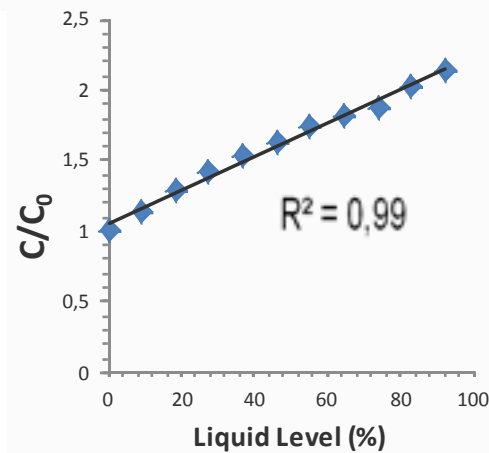
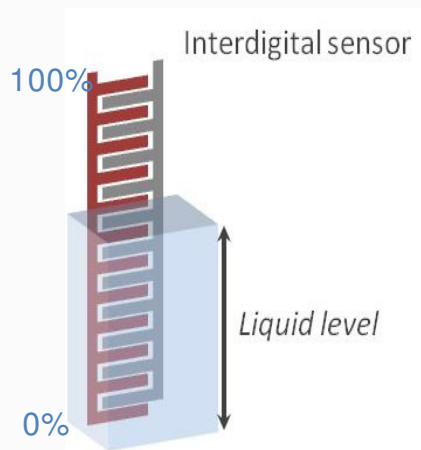
Processing

Characterization

Engineering

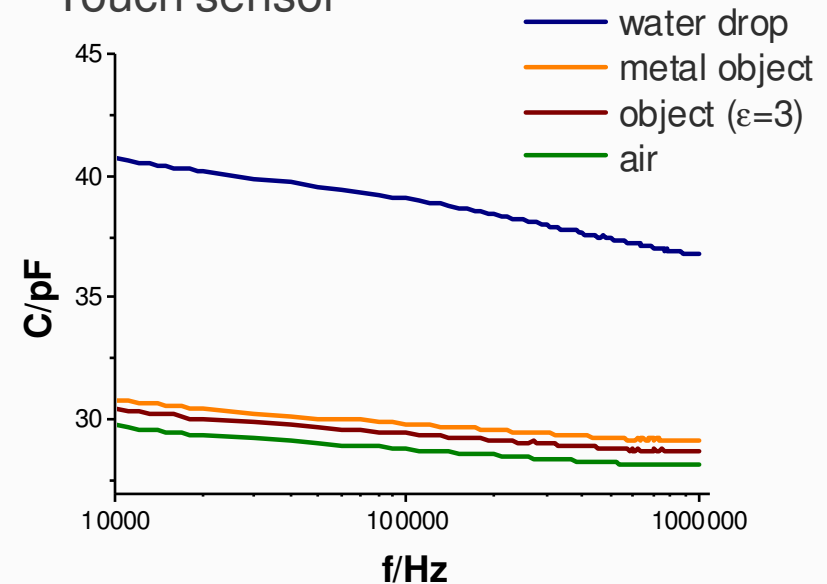
Performance evaluation

Liquid level detection



- Linear behavior.
- Good reproducibility.

Touch sensor



- Sensivity to different objects with low dielectric constant.
- Good reproducibility.

Capacitive printed sensors

Numerical simulation

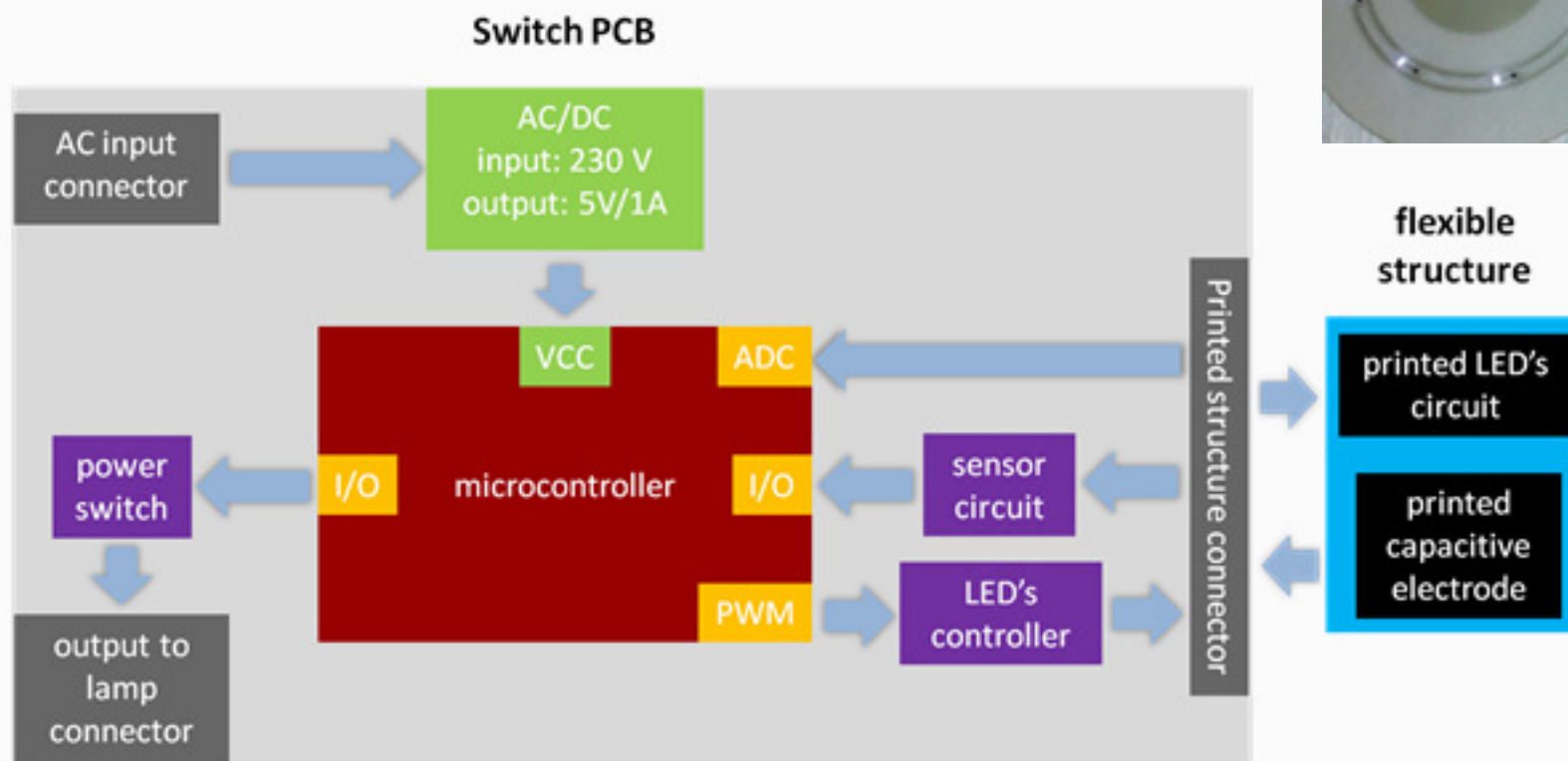
Processing

Characterization

Engineering

Example 1

Proximity sensor with LED indicator



Capacitive printed sensors

Numerical simulation

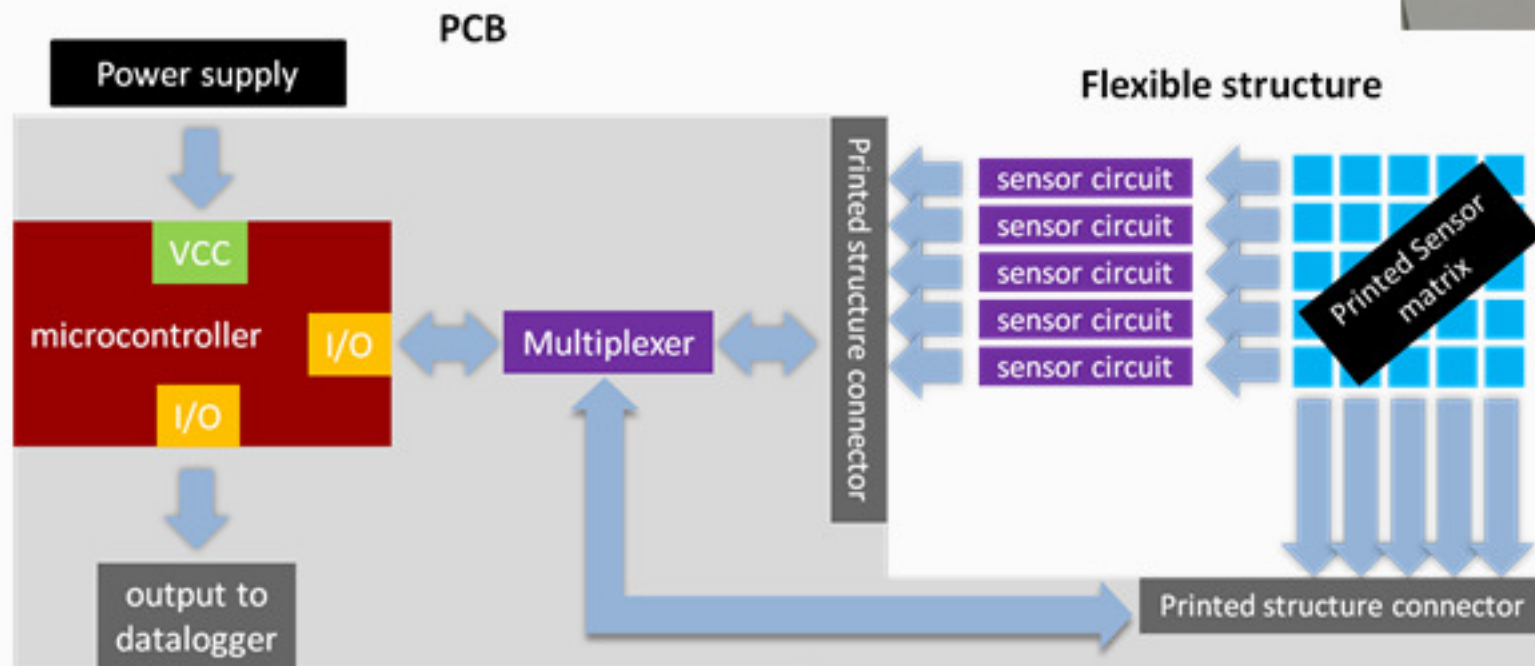
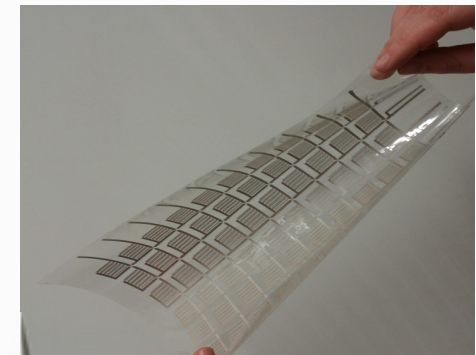
Processing

Characterization

Engineering

Example 2

sensor matrix for dielectric object detection



A case study



SENSE | Development of solution embedded sensing and/or printed electronics integrated on fuel tank.

GOALS | The objective of the work is to develop R&D activities that enhance innovation in sensorized structures.

OUTPUTS | Technologic demonstrator with integrated sensing multi-monitoring system: structure analysis system, fuel level and temperature sensors.

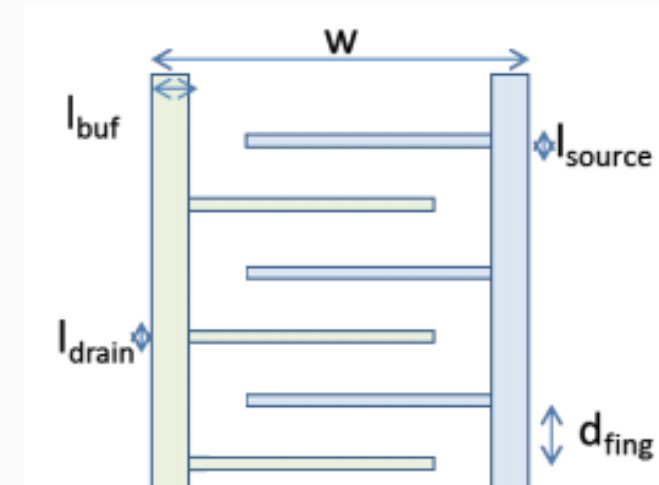
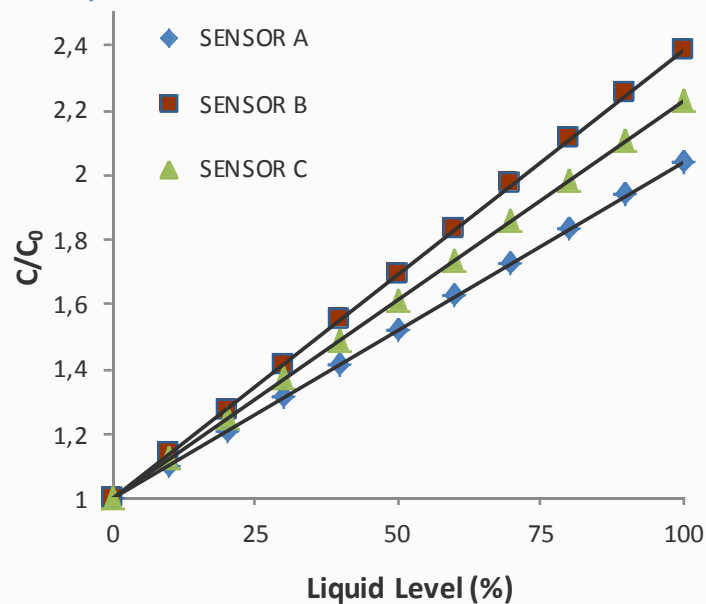
A case study: Sense Project

Numerical Simulation

Goals

- ▶ Increase fuel level sensibility;
- ▶ Decrease the sensibility to fuel drops.

Liquid with $\epsilon=3$



Sensor	I_{source} mm	I_{drain} mm	d_{fing} mm	Slope C/C_0	Drop 5% sensor size
A	1.00	1.00	1.00		
B	2.00	2.00	4.00	2.39	1.92
C	1	1	3	2.2	2.24

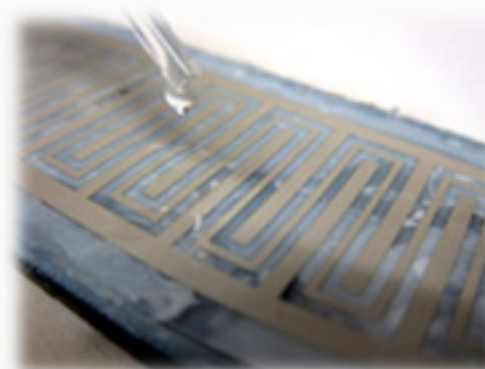
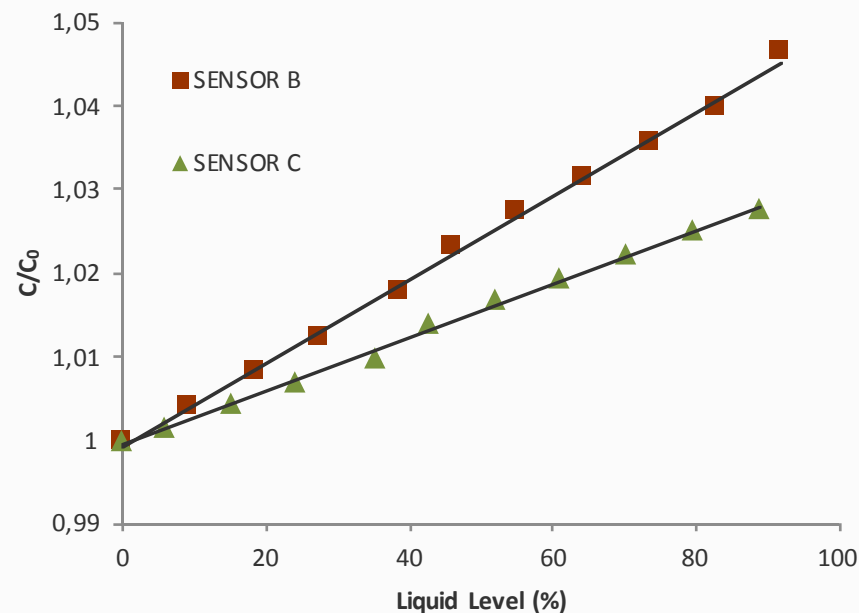
Best performance

A case study: Sense Project

Performance evaluation

Sensor B and C

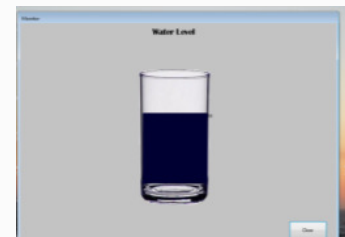
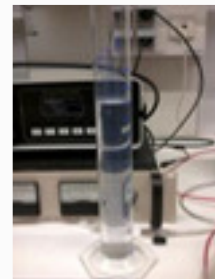
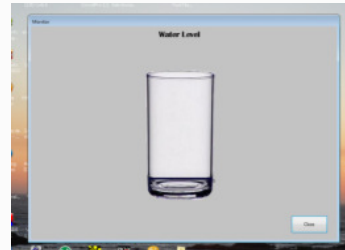
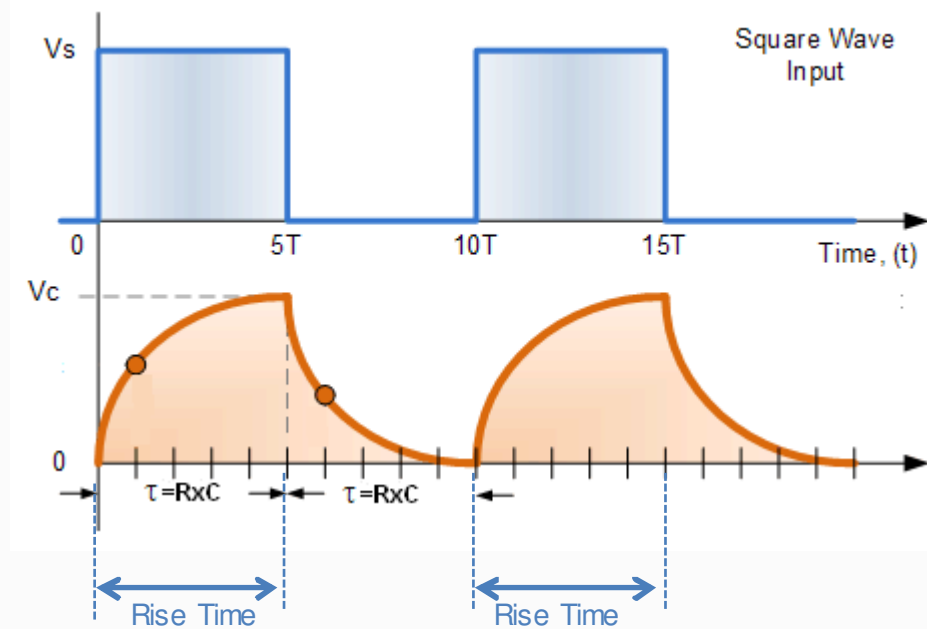
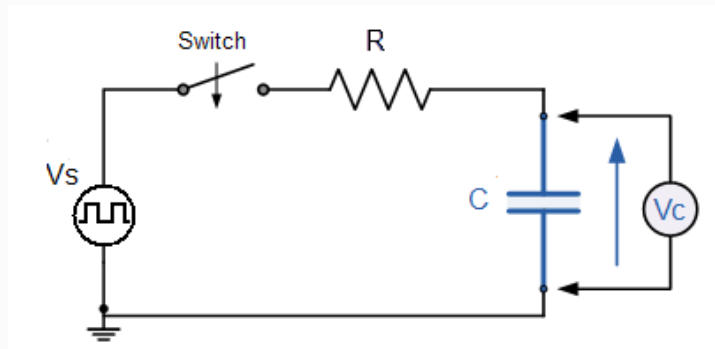
Sensitivity to liquid with low ϵ (~ 3)



Insensitivity to liquid drops

Number of drops	SENSOR B Output Signal
10	0.0%
20	0.1%
30	0.3%
50	0.7%

A case study: Sense Project Engineering



Measuring rise time and fix the R value,
the C is proportional to rise time.

Final Notes

- **An integrated strategy is necessary in order to successfully upscale R&D systems to pilot and production processes:**
 - Proof-of-concept;
 - In house” “market test” production (pre-series)
 - Bridge the gap between pre-series and full scale production - Valley of death;

Final Notes

Focus on integrated sensing systems:

- Integrated/added functionality;
- Added-value;
- Interconnectivity and hardware integration;
- Interactivity and availability of information;

Final Notes

- Moving towards all printed and all-integrated flat film electronics – still a way to go... ;
- Certification and quality control processes need to be developed concurrently with engineering and Up-scaling processes;



Centre for Nanotechnology
and Smart Materials

Thank you

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